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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC139

Dual 2-to-4-line Decoders/Demultiplexers



ADE-205-445 (Z)
1st. Edition
Sep. 2000

Description

The HD74HC139 contains two independent two-to-four-line decoders each with a single active low enable input (1G or 2G). Data on the select inputs (1A and 1B or 2A and 2B) cause one of the four normally high outputs to go low.

Features

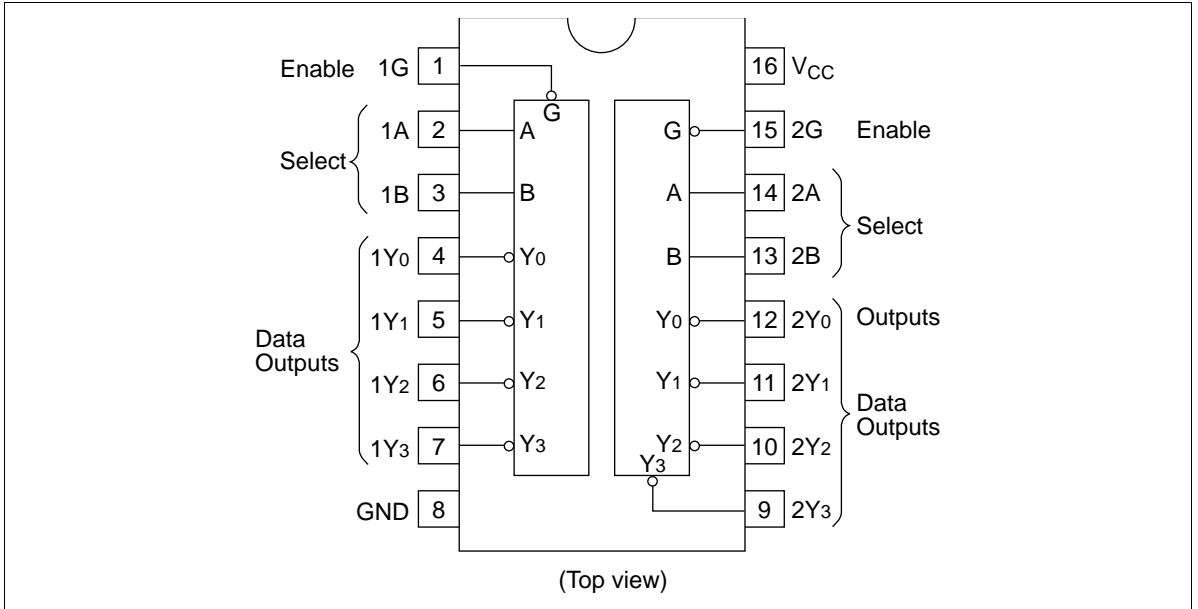
- High Speed Operation: t_{pd} (A, B to Y, 4 levels) = 14 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ V to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

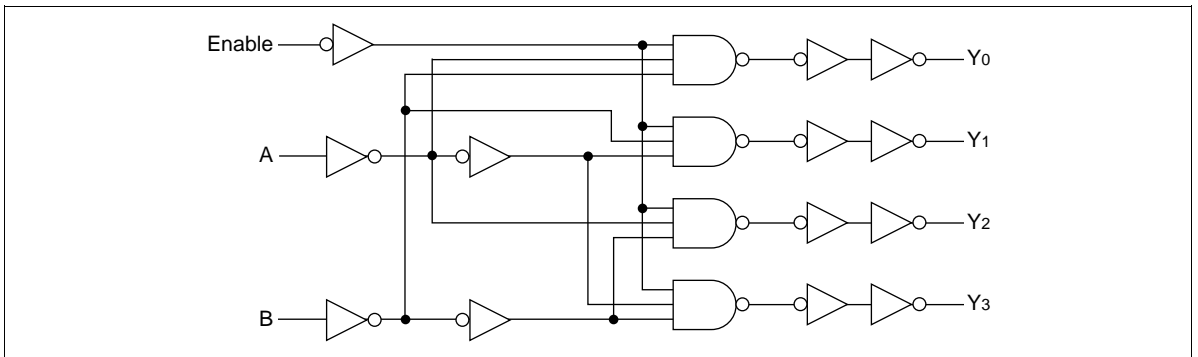
Inputs

Enable	Select		Outputs			
G	B	A	Y_0	Y_1	Y_2	Y_3
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	L	H	H	L	H	H
L	H	L	H	H	L	H
L	H	H	H	H	H	L

Pin Arrangement



Logic Diagram (1/2)



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

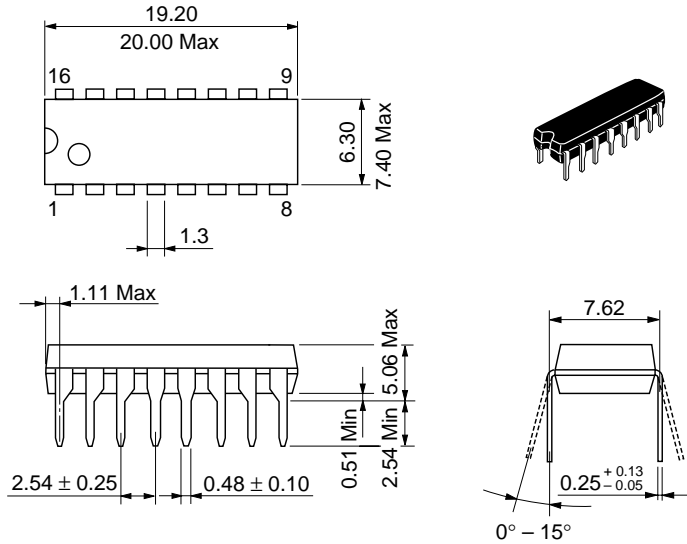
HD74HC139

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Propagation delay time	t_{PHL}	2.0	—	—	150	—	190	ns	Select to any output (4 levels)	
		4.5	—	15	30	—	38			
		6.0	—	—	26	—	33			
		2.0	—	—	150	—	190			ns
		4.5	—	13	30	—	38			
		6.0	—	—	26	—	33			
	t_{PLH}	2.0	—	—	150	—	190	ns	Select to any output (5 levels)	
		4.5	—	18	30	—	38			
		6.0	—	—	26	—	33			
		2.0	—	—	150	—	190			ns
		4.5	—	18	30	—	38			
		6.0	—	—	26	—	33			
	t_{PHL}	2.0	—	—	160	—	200	ns	Enable to any output	
		4.5	—	19	32	—	40			
		6.0	—	—	27	—	34			
		2.0	—	—	160	—	200			ns
		4.5	—	16	32	—	40			
		6.0	—	—	27	—	34			
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns		
	t_{THL}	4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Input capacitance	C_{in}	—	—	5	10	—	10	pF		

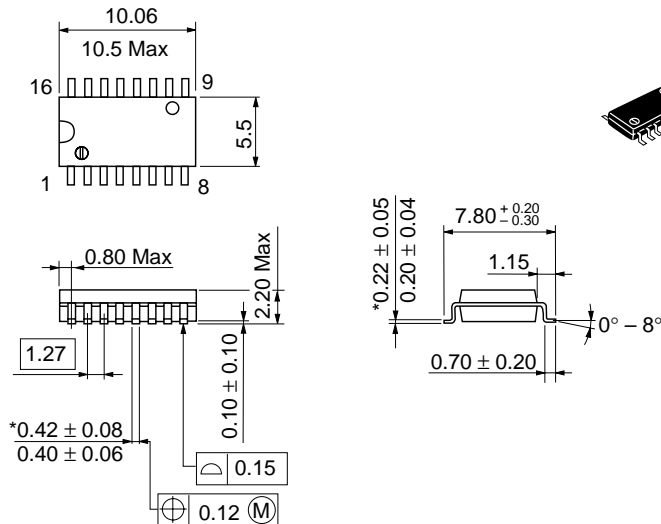
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

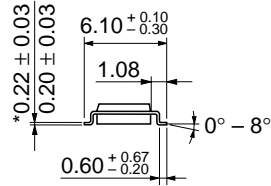
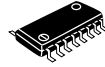
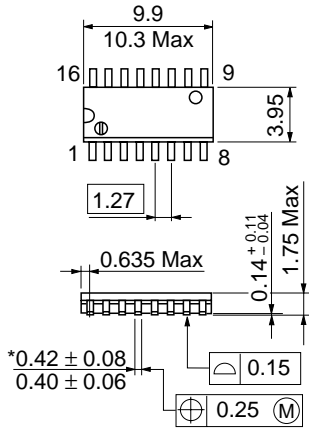
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

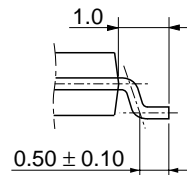
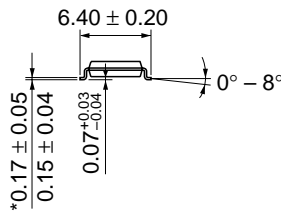
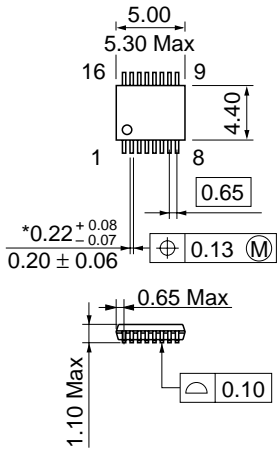
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-16DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.05 g

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